

PCN Number:	20230630000.0		PCN Date:	June 30, 2023																								
Title:	Datasheet for XTR11x																											
Customer Contact:	Change Management team	Dept:	Quality Services																									
Change Type:	Electrical Specification																											
PCN Details																												
Description of Change:																												
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.  XTR115, XTR116 SBOS124B – JANUARY 2000 – REVISED JUNE 2023 <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="text-align: left;">Changes from Revision A (November 2003) to Revision B (March 2022)</th> <th style="text-align: right;">Page</th> </tr> </thead> <tbody> <tr> <td>• Updated the numbering format for tables, figures, and cross-references throughout the document.....</td> <td style="text-align: right;">1</td> </tr> <tr> <td>• Added <i>Pin Functions, ESD Ratings, Thermal Information, Recommended Operating Conditions, and Electrical Characteristics</i> tables, and <i>Detailed Description, Overview, Functional Block Diagram, Feature Description, Application and Implementation, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information</i> sections.....</td> <td style="text-align: right;">1</td> </tr> <tr> <td>• Added <i>Pin Functions</i> table.....</td> <td style="text-align: right;">3</td> </tr> <tr> <td>• Changed operating temperature minimum value from –55°C to –40°C in <i>Absolute Maximum Ratings</i></td> <td style="text-align: right;">4</td> </tr> <tr> <td>• Deleted thermal resistance, θ_{JA} specification of 150 °C/W from <i>Electrical Characteristics</i>; added a <i>Thermal Information</i> table, with $R_{\theta JA} = 128.2$ °C/W and other detailed thermal parameters.....</td> <td style="text-align: right;">4</td> </tr> <tr> <td>• Changed span error test condition from: $I_{IN} = 250$ µA to 25 mA to: $I_{OUT} = 250$ µA to 25 mA in <i>Electrical Characteristics</i></td> <td style="text-align: right;">5</td> </tr> <tr> <td>• Changed V_{REF} voltage accuracy vs load typical value from ±100 ppm/mA to ±200 ppm/mA in <i>Electrical Characteristics</i></td> <td style="text-align: right;">5</td> </tr> <tr> <td>• Changed bias current vs temperature typical value from 150 pA/°C to 300 pA/°C in <i>Electrical Characteristics</i></td> <td style="text-align: right;">5</td> </tr> <tr> <td>• Changed <i>Basic Circuit Connections</i> application diagram.....</td> <td style="text-align: right;">9</td> </tr> <tr> <td>• Changed <i>External Transistor</i> applications information section to incorporate additional guidance regarding transistor power dissipation and thermal concerns.....</td> <td style="text-align: right;">10</td> </tr> <tr> <td>• Added <i>Circuit Stability</i> application information section.....</td> <td style="text-align: right;">12</td> </tr> </tbody> </table>					Changes from Revision A (November 2003) to Revision B (March 2022)	Page	• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1	• Added <i>Pin Functions, ESD Ratings, Thermal Information, Recommended Operating Conditions, and Electrical Characteristics</i> tables, and <i>Detailed Description, Overview, Functional Block Diagram, Feature Description, Application and Implementation, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information</i> sections.....	1	• Added <i>Pin Functions</i> table.....	3	• Changed operating temperature minimum value from –55°C to –40°C in <i>Absolute Maximum Ratings</i>	4	• Deleted thermal resistance, θ_{JA} specification of 150 °C/W from <i>Electrical Characteristics</i> ; added a <i>Thermal Information</i> table, with $R_{\theta JA} = 128.2$ °C/W and other detailed thermal parameters.....	4	• Changed span error test condition from: $I_{IN} = 250$ µA to 25 mA to: $I_{OUT} = 250$ µA to 25 mA in <i>Electrical Characteristics</i>	5	• Changed V_{REF} voltage accuracy vs load typical value from ±100 ppm/mA to ±200 ppm/mA in <i>Electrical Characteristics</i>	5	• Changed bias current vs temperature typical value from 150 pA/°C to 300 pA/°C in <i>Electrical Characteristics</i>	5	• Changed <i>Basic Circuit Connections</i> application diagram.....	9	• Changed <i>External Transistor</i> applications information section to incorporate additional guidance regarding transistor power dissipation and thermal concerns.....	10	• Added <i>Circuit Stability</i> application information section.....	12
Changes from Revision A (November 2003) to Revision B (March 2022)	Page																											
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1																											
• Added <i>Pin Functions, ESD Ratings, Thermal Information, Recommended Operating Conditions, and Electrical Characteristics</i> tables, and <i>Detailed Description, Overview, Functional Block Diagram, Feature Description, Application and Implementation, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information</i> sections.....	1																											
• Added <i>Pin Functions</i> table.....	3																											
• Changed operating temperature minimum value from –55°C to –40°C in <i>Absolute Maximum Ratings</i>	4																											
• Deleted thermal resistance, θ_{JA} specification of 150 °C/W from <i>Electrical Characteristics</i> ; added a <i>Thermal Information</i> table, with $R_{\theta JA} = 128.2$ °C/W and other detailed thermal parameters.....	4																											
• Changed span error test condition from: $I_{IN} = 250$ µA to 25 mA to: $I_{OUT} = 250$ µA to 25 mA in <i>Electrical Characteristics</i>	5																											
• Changed V_{REF} voltage accuracy vs load typical value from ±100 ppm/mA to ±200 ppm/mA in <i>Electrical Characteristics</i>	5																											
• Changed bias current vs temperature typical value from 150 pA/°C to 300 pA/°C in <i>Electrical Characteristics</i>	5																											
• Changed <i>Basic Circuit Connections</i> application diagram.....	9																											
• Changed <i>External Transistor</i> applications information section to incorporate additional guidance regarding transistor power dissipation and thermal concerns.....	10																											
• Added <i>Circuit Stability</i> application information section.....	12																											
The datasheet number will be changing.																												
Device Family	Change From:	Change To:																										
XTR11x	SBOS124A	SBOS124B																										
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/XTR115																												
Reason for Change:																												
To accurately reflect device characteristics.																												
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																												
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device																												
Changes to product identification resulting from this PCN:																												
None.																												

Product Affected:			
XTR115U	XTR115U/2K5	XTR115UA	XTR115UA/2K5
XTR116U	XTR116U/2K5	XTR116UA	XTR116UA/2K5

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disdaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.